Overview

HP Elite x2 1012 G2



- 1. Infrared camera
- 2. Infrared camera light
- 3. Audio-out/Audio-in combo jack
- 4. USB-A 3.0
- 5. Power LED
- 6. USB Type-C[™] with Thunderbolt
- 7. Micro SIM Card Slot*
- 8. Kickstand
- 9. Application Launch Button (Default OneNote)

- 10. Clip
- 11. Select (Programmable Function Button)
- 12. Erase (Programmable Function Button)
- 13. Tip
- 14. Keyboard guide pins
- 15. Webcam light
- 16. Webcam
- 17. Microphones
- 18. Front-firing speakers

*only available on configurations with WWAN enabled



Overview



- 1. Power
- 2. Volume Up/Volume down
- 3. Micro SD Memory Card Slot
- 4. Security Cable Slot
- 5. Pen Lanyard Slots



Overview



- 1. Camera
- 2. Camera Flash

3. Fingerprint Sensor (optional)



Overview



HP Elite x2 1012 G2 Collaboration Keyboard



Overview



Technical Specifications

At A Glance

- Designed for excellent mobility, this stylish and thin 2-in-1 design is built to the standards of Elite durability
- The quiet design and up to 10 hours and 15 minutes of battery life¹ lets you work, surf, and connect with colleagues
- Windows 10 versions
- 7th Generation Intel[®] Core[™] (U-series) processors, some with vPro[™] support²
- 12.3" diagonal ultra-slim LED-backlit better than QHD (2736 x 1824) Multi-Touch Display
- Solid State Drives up to 512GB including FIPS 140.2 (CIS only);0PAL 2 drives support up to 256GB PCLe NVMe drives support up to 1024GB
- Weight starting at 810g for Tablet
- Height starting at 8.05mm for Tablet
- Passed MIL-STD 810G testing:
 - MIL-STD is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. MIL-STD test results are not a guarantee of future performance under these test conditions. Damage from drops requires separately purchase Accidental Damage Protection HP Care Pack.
- Audio by Bang & Olufsen
- Optional IR camera (mutually exclusive with WiGig)
- Dual microphone array with HP Advanced Noise Reduction Software
- Front and Back facing camera and webcam
- Supports a broad range of wireless broadband and Wi-Fi options for connectivity on the go
- Optimized security using industry standard technologies such as TPM2.0, optional integrated fingerprint reader and an optional smart card reader in the optional Advanced keyboard
- Passed EN 60601-1-2:2007 and IEC 60601-1-2:2014 tests
- ENERGY STAR[®] certified. EPEAT[®] Gold registered where applicable/supported. Registration may vary by country. See www.epeat.net for registration status by country.
- Protect your device and data using the latest HP security technology solutions: HP Sure Start, HP BIOSphere and HP Client Security.
- Standard commercial 1 year limited warranty with extended service available with optional HP Care Packs.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

¹ Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

² vPro[™] support not available on all configurations.



Technical Specifications

PRODUCT NAME

HP Elite x2 1012 G2

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64 ¹
	Windows 10 Pro 64 (National Academic License) ²
	Windows 10 Home 64 ¹
	Windows 10 Home Single Language 64 ¹
Web-only Support	Windows 10 Enterprise 64

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7

In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com

PROCESSOR*

7th Generation Intel® Core™ i3, i5 and i7 Processors:

Intel[®] Core™ i3-7100U with Intel[®] HD Graphics 620 (2.4 GHz, 3 MB cache, 2 cores)

Intel® Core™ i5-7200U with Intel® HD Graphics 620 (2.5 GHz, up to 3.1 GHz with Intel® Turbo Boost Technology**, 3 MB cache, 2 cores)

Intel[®] Core[™] i5-7300U with Intel[®] HD Graphics 620 (2.6 GHz, up to 3.5 GHz with Intel[®] Turbo Boost Technology**, 3 MB cache, 2 cores), vPro[™] Support

Intel® Core™ i7-7600U with Intel® HD Graphics 620 (2.8 GHz, up to 3.9 GHz with Intel® Turbo Boost Technology**, 4 MB cache, 2 cores), vPro™ Support

* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology.. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering is not a measurement of higher performance. ** Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

CHIPSET

Integrated with processor



Technical Specifications

GRAPHICS

Intel[®] HD Graphics 620

DISPLAY

Internal

Touch screen

12.3" diagonal BrightView LED-backlit better than QHD* UWVA eDP 1.3 Ultra-slim (2736 x 1824) Touch screen Chemicallystrengthened Corning® Gorilla® Glass 4 top cover directly bonded to display

Refresh Rate	60 Hz		
Brightness	450 nits (maximum)		
Pixel Resolution	Format 2736 x 1824 (better than QHI		
	Configuration	RGB Stripe	
Interface	eDP 1.3		
LCD Mode	IPS/FFS/VA		
PPI	268 ppi		
Viewing Angle	UWVA 85/85/85/85 (Left/Right/Down/Up)		

External

24-bit + 8 bit alpha channel (standard) Up to 30-bit per pixel color depth (Wide Color Gamut)

* HD content required to view HD images. NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

Internal Storage* - supports M.2 SSD SS 2280

- 128 GB SATA-3 SS VALUE SSD
- 256GB 2280 M2 PCIe-3x4 SS NVMe TLC
- 256GB 2280 M2 SATA-3 Self Encrypted OPAL2 TLC
- 256GB 2280 PCIe NVMe Value
- 360GB 2280 PCIe-3x4 NVMe TLC
- 512GB 2280 M2 PCIe-3x4 SS NVMe TLC
- 512GB 2280 PCIe NVMe Value
- 512GB 2280 M2 SATA-3 Three Layer Cell Federal Information Processing Standard (FIPS 140.2 available via CIS only)
- 1024 GB 2280 PCIe-3x4 NVMe TLC

* For SSD's, GB=1 billion bytes. TB=1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) of system disk is reserved for system recovery software.

Expansion Storage



Technical Specifications

Micro SD Media Reader Slot - Supports microSD, microSDHC, microSDXC, supporting expansion up to 2TB

MEMORY

LPDDR3-1866 (Transfer rates up to 1866 MT/s) Supports Dual Channel Memory Soldered Down

Standard 4 GB Total System Memory 8 GB Total System Memory

Maximum Up to 16 GB

NETWORKING/COMMUNICATIONS

Wireless

Support for a broad range of secure, integrated wireless LAN/Bluetooth and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a factory-only configurable feature only. Standalone GPS is also available (factory configurable only) and is supported via combo card. WiGig is also available with the optional LAN/Bluetooth/WiGig combo module for seamless, no wires docking*** (factory configurable only)

Wireless WAN (WWAN)*

HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module HP lt4120 Qualcomm® Snapdragon™ X5 LTE Mobile Broadband Module HP hs3210 HSPA+ Mobile Broadband Module

Wireless LAN (WLAN)**

Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo (vPro) Intel® Dual Band Wireless-AC 8265 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo (non-vPro) Intel® Tri Band Wireless-AC 18265 802.11a/b/g/n/ac (2x2) and Bluetooth® 4.2 + WiGig Combo***

Standalone GPS****

HP Graff GNSS Module

* WWAN is an optional feature and requires factory configuration. WWAN connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

**Wireless access point and Internet service is required and is not included. Availability of public wireless access points limited.

***The WiGig-compatible notebook or tablet must be positioned within 1.2 m (4 ft) and without obstruction in the line of sight of the wireless dock. HP Advanced Wireless Docking is compatible with the HP Elite x2 1012 G2 with an optional installed Intel Tri Band Wireless AC with WiGig Combo card available at the time of purchase. WiGig docking requires the addional purchase of the HP Advanced Wireledd Docking Station. IR camera is not available when WiGig is selected.



Technical Specifications

****Standalone GPS is an optional feature and requires factory configuration. GPS and WWAN are mutually exclusive.



Technical Specifications

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen Dual speakers (front facing) Dual microphone array with echo cancellation, noise suppression Headphone line-out and microphone-in (combo) HP Advanced Noise Reduction Software

Camera – Front

Integrated 5 MP (1080p)

- 1080p format for video
- 5 MP for still capture
- Supports videoconferencing* and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1920x1080 resolution (1080p) and up to 30 fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing*
- Improved low light sensitivity
- Improved dynamic range

Camera – Back

Integrated 8 MP with flash (1080p)

- 1080p format for video
- 8 MP for still capture
- Supports videoconferencing* and still image capture
- High quality auto focus lens
- Video capture at various resolutions up to 1920x1080 resolution (1080p) and up to 30fps
- M-JPEG compression supports higher frame rates for video capture and videoconferencing*
- Improved low light sensitivity
- Improved dynamic range

IR Camera (mutually exclusive with WiGig)

Integrated VGA IR camera w/ IR LED emitters that meets Microsoft Hello face recognition certification for secure authentication.

* Internet access required.

ACTIVE PEN

HP Active Pen with Bluetooth® App Launch

Pen Technology	Wacom AES
Digitizer	N/A, shared with touch
Dimensions	147.4 x 9.5 mm
Weight	17.5 g
Power	AAAA battery and 319 coin cell x2
System Requirements	Windows 10
Tip Diameter	1 mm
Pen Tips	Three extra elastomer pen tips for replacement



Technical Specifications

Pressure Sensitivity (Y/N)	Yes (2048 levels)
(1/1)	
Buttons (Y/N)	Yes, 3
Resolution	2540 ррі
Report rate	133hz
Hover Capability (Y/N)	Yes
Hover Height (mm)	10mm+
Palm Rejection (Y/N)	Yes
Tilt Angle (Y/N)	>60 degrees from vertical
Battery Life Based on	
Continuous Usage	7.5 month+

OPTIONAL KEYBOARDS

Optional HP Elite x2 1012 G2 Collaboration Keyboard*

Kit contents	HP Elite x2 1012 G2 Collaboration Keyboard and documentation
Weight	.78 lb (353 g)

Optional HP Elite x2 1012 G1 Advanced Keyboard*

Kit contents	HP Elite x2 1012 G1 Advanced Keyboard and documentation
Key Features	Smart card reader FIPS-201 compliant.
	Security - Near Field Communications (NFC) Module

Weight .992 lb (450 g)

*Sold as an optional feature

Keyboard Features (common to both Collaboration and Advanced Keyboards)

- Backlit
- HP DuraKeys
- 1.3mm key travel
- 18.4mm pitch
- ClickPad™ (91 x 51 mm) with image sensor, multi-touch gestures enabled, on/off function and LED indicator
- 165° max opening angle
- Docking connector to tablet
- Wipeable back cover
- Full size 81/82-key island-style backlit keyboard with full row of function keys and LED indicators

ClickPad

Glass with chemical etched surface Supports 2-way scroll Taps enabled as default Gestures enabled by default - 2 Finger Scrolling, 2 Finger Zoom (Pinch)

Keyboard Features (Collaboration Keyboard only)



Technical Specifications

- F1 Display Switching F2 - Blank F3 – Brightness Down F4 - Brightness Up F5 - Speaker Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Backlight Toggle
- F10 Number Lock
- F11 Wireless On/Off
- F12 Calendar

Dedicated Skype for Business keys:

Present Call answer/initiate Call end Delete

Keyboard Features (Advanced Keyboard only)

Function Keys

F1 - Blank F2 - Blank F3 - Sleep F4 - Display Switching F5 - Speaker Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Brightness Down F10 - Brightness Up F11 - Backlight Toggle F12 - Wireless On/Off

SOFTWARE AND SECURITY

Preinstalled Software with Windows Operating System

HP BIOS

HP BIOSphere Gen3¹ HP Sure Start Gen3² HP DriveLock | HP Automatic DriveLock BIOS Update via Network Master Boot Record Security



Technical Specifications

Power On Authentication Secure Erase³ Absolute Persistence Module⁴ Pre-boot Authentication

Communication / Connectivity

HP Mobile Connect Pro⁵ Native Miracast Support⁶ HP LAN-WLAN Protection HP MAC Address Manager (select models only) HP SureConnect HP Velocity

HP Value Add Software

HP ePrint Driver + JetAdvantage⁷ HP Hotkey Support - CMIT HP Jumpstart HP Support Assistant HP Noise Cancellation Software

Microsoft Products

Buy Office Bing Search Skype⁸

Manageability

HP Driver Packs⁹ HP SoftPaq Download Manager (SDM) HP System Software Manager (SSM)⁹ HP BIOS Config Utility (BCU)⁹ HP Client Catalog⁹ HP MIK for Microsoft SCCM⁹ LANDESK Management¹⁰ Discover HP Touchpoint Manager¹¹

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Client Security Software

HP Client Security

- HP Security Manager (including Credential Manager and Password Manager)
- HP Drive Lock
- HP Fingerprint Sensor
- HP Password Manager
- Absolute Persistence Module
- Power On Authentication
- Microsoft Defender¹²
- HP Workwise¹³



Technical Specifications

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

Security Hardware

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) HP Fingerprint Reader (selectd models) Integrated VGA IR camera with IR LED emitters that meets Microsoft Hello face recognition certification for secure authentication (select models)

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- 1. BIOSphere Gen3 requires Intel[®] or AMD[®] 7th generation processors.
- 2. Available on HP Elite products equipped with Intel[®] 7th generation processors as well as the HP Pro x2 612 G2.
- 3. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
- 4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 5. HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to www.hp.com/go/mobileconnect
- 6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast
- 7. Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter).
- 8. Skype is not offered in China.
- 9. Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement
- 10. Subscription required.
- 11. HP Touchpoint Manager requires purchase of a subscription and supports Android[™], iOS and Windows 7 or higher operating systems and PCs, notebooks, tablets and smartphones from various manufacturers. Not available in all countries see www.hp.com/touchpoint for availability information
- 12. Opt in and internet connection required for updates.
- 13. HP Workwise smartphone app is available as a free download on the App Store and Google Play. See requirements at www.hp.com/go/workwise

POWER

Power Supply

HP 45 W USB Type-C[™] AC adapter

- HP 65 W USB Type-C[™] AC adapter
 - USB Type-C[™] DC integrated cord (1.8m)
 - AC Power cord (1m)
 - AC Adapter Weight: 245g +/- 10g



Technical Specifications

Tablet – Battery

4-cell Long Life Polymer 47Whr (3055mAhr/cell)

- Voltage 7.7 V
- Supports HP Fast Battery Charging*

Battery Life**

Windows 10 battery time:

Up to 10 hours *

* Units enabled with 65w adapters or higher can support fast charging of the battery from 0-50% in 30 minutes while the system is off.

**Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight*

Tablet only Starting at 1.77 lbs (803 g)

Tablet with Travel Keyboard

2.55 lbs (1156 g)

Tablet with Advanced Keyboard

2.94 lbs (1333 g)

Dimensions - (w x d x h)*

Tablet

11.8 x 8.4 x 0.3 in (300 x 213.85 x 8.05 mm)

Tablet with Travel Keyboard 11.8 x 8.63 x 0.53 in (300 x 219.3 x 13.55 mm)

Tablet with Advanced Keyboard 11.8 x 8.6 x 0.6 in (300 x 219.3 x 16.65 mm)

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components.

*Values are preliminary and may be updated before product launch.

PORTS/SLOTS

Tablet

Ports

1 USB Type-C[™], supporting USB 3.1 (supports Thunderbolt[™] 3)

1 USB Type-A, supporting USB 3.0



Technical Specifications

1 Headphone /microphone combo

NOTE: For optimal performance, the HP x2 1012 G2 should charge from a USB Power Delivery, v2 compatible adapter or power source that offers 12V @ 3A.

Slots

1 Micro SIM drawer (optional)

1 Micro SD Media Reader Drawer -supports microSD, microSDHC, microSDXC

1 Lock slot

Advanced Keyboard

Ports

Slots

1 Smart card reader

SENSORS

Accelerometer Magnetometer Gyro ALS (Ambient Light Sensor) Proximity (SAR for WWAN) Hall Sensor

SERVICE AND SUPPORT

HP Services offers 3-year, 1-year and 90 day limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc.



Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	15 V
	Nominal Operating Amperage	4.33A
	Average Operating Power	7.21 W (non-charging)
	Max Operating Power	65 W
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	240 G, 2 ms, half-sine
Random Vibration	Operating	1.043 grms
	Non-operating	3.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)

STORAGE AND DRIVES

128 GB SATA-3 SS VALUE SSD	Drive Weight	0.02 lb (10 g)	
	Capacity	128 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	ATA-8, SATA 3.0	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		535 MB/s	515 MB/s
	Logical Blocks	250,069,680	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	mp]
	Features	ATA Security; DIPM; TRIM; DEVSLP	
256GB 2280 M2 PCIe-3x4	Drive Weight	0.02 lb (10 g)	
SS NVMe TLC	Capacity	256 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	PCIe NVMe Gen3X4	



Technical Specifications

	Performance	Maximum Sequential Read	Maximum Sequential Write	
		2600 MB/s	900 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	emp]	
	Features	ATA Security (Option) TRIM; L1.2		
256GB 2280 M2 SATA-3	Drive Weight	0.02 lb (10 g)		
Self Encrypted OPAL2	Capacity	256 GB		
TLC	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	ATA-8, SATA 3.0		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		530 MB/s	515 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	emp]	
	Features	ATA Security; TCG Opal 2.0 DIPM; TR	IM; DEVSLP	
256GB 2280 PCIe NVMe	Drive Weight	0.02 lb (10 g)		
Value	Capacity	256 GB		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		1700 MB/s	600 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	emp]	
	Features	ATA Security; TCG Opal 2.0 ; FIPS; TR		
360GB 2280 PCIe-3x4	Drive Weight	0.02 lb (10 g)		
NVMe TLC	Capacity	360GB		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe NVMe Gen3X4		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		1700 MB/s	600 MB/s	
	Logical Blocks	703,282,608		

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]



	Features	ATA Security (Option); TRIM; L1.2	
512GB 2280 M2 PCIe-3x4	Drive Weight	0.02 lb (10 g)	
SS NVMe TLC	Capacity	512 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2600 MB/s	1400 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	mp]
	Features	ATA Security; TRIM; L1.2	
512GB 2280 PCIe NVMe	Drive Weight	0.02 lb (10 g)	
Value	Capacity	512 GB	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		1700 MB/s	600 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	mp]
	Features	ATA Security; TCG Opal 2.0 ; FIPS; TRI	M; L1.2
512GB 2280 M2 SATA-3	Drive Weight	0.02 lb (10 g)	
Three Layer Cell Federal	Capacity	512 GB	
Information Processing Standard	Height	0.09 in (2.3 mm)	
Stanuaru	Width	0.87 in (22 mm)	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		530 MB/s	500 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient te	mp]
	Features	ATA Security; TCG Opal 2.0 ; FIPS; TRI	M; L1.2
1024 GB 2280 PCIe-3x4	Drive Weight	0.02 lb (10 g)	
NVMe TLC	Capacity	512 GB	
	Height	0.14 in (3.65 mm)	
	Width	0.87 in (22 mm)	



Technical Specifications

Interface	PCIe NVMe Gen3X4	
Performance	Maximum Sequential Read	Maximum Sequential Write
	1500 MB/s	980 MB/s
Logical Blocks	2,000,409,264	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security (Option); TRIM; L1.2	

SECURITY

HP Fingerprint Reader	Mobile Voltage Operation	3.0V-3.6V
/- · · · · · · ·	Operating Temperature	14° – 167°F (-10° – 75°C)
(Optional – available on the Tablet)	Current Consumption Image	36 mA peak
	Low Latency Wait for Finger	950 uA
	Capture Rate	30 cm/sec
	ESD Resistance	IEC 61000-4-2 4B (±15KV)
	Detection Matrix	200*1 (plus another secondary line) 508 dpi 10 mm sensor area

NETWORKING/COMMUNICATIONS

WWAN Modules

HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module

Technology/Operating bands	LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz, 850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz, 800 (Band 20), 700 (Band 28) MHz. HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 - MSC9
GPS	Standalone, A-GPS (MS-B and LTO)
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	LTE: 150 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)



Technical Specifications

Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

* Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP hs3210 HSPA+ Mobile Broadband Module*

Technology/Operating bands	HSPA+: 2100 (Band1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 MHz (Band 5), 900 (Band 8) MHz
Wireless protocol standards	WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification E-GPRS: Class B, Multi-slot class 33, coding schemes CS1 - CS4 and MSC1 - MSC9
Maximum data rates	HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)
	E-GPRS: 296 kbps (Download), 236.8 kbps (Upload) GPRS: 107 kbps (Download), 85.6 kbps (Upload)
Maximum output power	HSPA+: 24 dBm E-GPRS 1800/1900: 26 dBm E-GPRS 850/900: 27 dBm GPRS 1800/1900: 30 dBm GPRS 850/900: 33 dBm
Maximum power consumption	HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,800 mA (peak); 700 mA (average)
Form Factor	М.2, 2242-S3 Кеу В
Weight	6 g
Dimensions (Length x Width x Thickness)	1.65 x 8.66 x 0.09 in (42 x 22 x 2.38 mm)



Technical Specifications

* Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP lt4225 LTE/EV-DO Gobi™ 4G Mobile Broadband Module*

Technology/Operating bands	LTE: 1400 (Band 11), 800 (Band 18, Japan 800 lower) EV-DO: 800 (BC0), 2100 (BC6) MHz
Wireless protocol standards	3GPP Release 8 LTE Specification EVDO Release 0 and Release A
GPS	Standalone
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	LTE: 100 Mbps (Download), 50 Mbps (Upload) CDMA 1x: 153.6 kbps (Download), 153.6 kbps (Upload) EVDO Rev.A: 3.1 Mbps (Download), 1.8 Mbps (Upload)
Maximum output power	LTE: 23 dBm CDMA/EVDO: 24dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) EVDO: 900mA (peak); 720mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

(Length x Width x Thickness)

* Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

HP lt4226 LTE/HSPA+ Gobi 4G Module*

Technology/Operating bands	LTE: 2100 (Band 1), 800 (Band 19, Japan 800 upper), 1450 (Band 21) HSPA+: 2100 (Band 1), 800 (Band 6), 800 (Band 19) MHz
Wireless protocol standards	3GPP Release 8 LTE Specification WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification
GPS	Standalone
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	LTE: 100 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B



Technical Specifications

8 x 0.09 in (42 x 30 x 2.3 mm)

HP hs3210 WW HSPA+ w/o GPS

Technology/Operating bands	LTE: 2100 (Band 1), 800 (Band 19, Japan 800 upper), 1450 (Band 21) HSPA+: 2100 (Band 1), 800 (Band 6), 800 (Band 19) MHz
Wireless protocol standards	3GPP Release 8 LTE Specification WCDMA R99, 3GPP Release 5, 6 and 7 UMTS Specification
GPS	Standalone, A-GPS
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	LTE: 100 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21.6 Mbps (Download), 5.76 Mbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	М.2, 3042-S3 Кеу В
Weight	6 g
Dimensions (Length x Width x Thickness)	1.65 x 1.18 x 0.09 in (42 x 30 x 2.3 mm)

*Mobile Broadband is an optional feature and requires factory configuration. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

<u>HP GPS</u>

Technology	Standalone GPS, GLONASS
Operating bands	GPS L1 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum power consumption	Active mode (continuous): 67 mA (peak); 26 mA (average)
Form Factor	М.2, 3042-53 Кеу В
Weight	4.3 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

WLAN MODULES



Technical Specifications

Band Wireless	<u>s-N 18265 802.11 ac 2x2 WiFi + BT (</u>	4.2 +Wi	<u>Gig combo adaptor (vl</u>	Pro™)
	Form Factor	Combo Module, M.2 2230-S3-A		
	Dimensions	22.00±0.15mm by 30.00±0.15mm by 2.38mm max.		
	Weight	4 gran	าร	
	Operating Voltage	3.3 Vo	lts	
	Wireless LAN Standards	IEEE 802.11ad		
	Interoperability	Wi-Fi o	ertified MAC and Physi	cal Layer
		ratifie	d)	Protocol Adaption Layers (PALs) (Not yet
			reless Display Extension reless Serial Extension	
	Frequency Band	802.17		orted
		57 – 6		2, 3, 4) but only 2 (bands 2 and 3) are
				ntries on the planet. HP will support only
			2 and 3, 59-64 GHz	incres on the planet. The will support only
		Note: freque		unlicensed operation at these
	Antenna Structure	 Active, extended coverage multiple antenna array of 24 elements Almost full spherical RF coverage by having Front 6 elements- horizontal + 7 elements- vertical North 3 Patch West 2 Dipole + 2 Patch 		
	(Remote Front End Module,			
	R-FEM)			
			ast 4 Dipole side supports one R-F	EM3
			••	
	Data Rates (RAW)	Dock side supports one or two R-FEMs MCS Rate, Mbit/s Modulation		Modulation
			, .	
		0	27.5	π/2-BPSK
		1	385.0	π/2-BPSK
		2	770.0	π/2-BPSK
		3	962.5	π/2-BPSK
		4	1155.0	π/2-BPSK
		5 6	1251.25 1540.0	π/2-BPSK π/2-QPSK
		о 7	1925.0	π/2-QPSK
		8	2310.0	π/2-QPSK
		9	2502.5	π/2-QPSK
		10	3080.0	π/-16QAM
		11	3850.0	π/-16QAM
		12	4620.0	π/-16QAM

Intel® Tri Band Wireless-N 18265 802.11 ac 2x2 WiFi + BT 4.2 +WiGig combo adaptor (vPro™)



Network Architecture Models	Ad-hoc (Peer to Peer)				
Wireless Display Extension (WDE) WGA WDE support	AV PAL (WDE) as defined by WiGig alliance			
	AVC/MPEG support - encoder	WDE supports generation of MPEG-PS / MPEG-PES packets as described in the WDE standard WDE supports AVC (H264) encoder, intra only, 4:4:4 Chroma subsampling. Different visually lossless and lossy scenarios are supported by configuration			
	AVC/MPEG support – decoder	H.264 CAVLC 4:4:4 I-only sub sampling is supported			
	Type of Interface	 Client device side DP (Display port) v1.2a – HBR (1, 2, 4 lanes) Dock device side DP v1.2 – HBR (1, 2, 4 lanes) HDMI v1.4a (through external Hub or cable adapter) DP++ compatible 			
		Note : DP v1.2 is backward compatible with DP v1.1a			
	DP Resolution and Frame Rate Support	DP will support the following resolutions 640x480, 1280x720, 1920x1080, 1920x1200, 2560x1440, 2560x1600 and frame rates – 24, 25, 30, 50 and 60 Hz All resolutions are in progressive mode (no interlaced supported) Specifically, the following resolutions and frame rats will be supported • 640x480p60 • 1280x720p60 • 1920x1080p60 • 1920x1200p60 • 2560x1440p60 • 2560x1600p60 Note: resolution and refresh rate may			
	HDMI Resolution and Frame Rate Support	 change in situations where there is a bad link or strict limits on TDP HDMI supports the following resolution and frame rates – 640x480p60 1280x720p60 1920x1080p60 			



Color space support DP & HDMI Color Depth Support Dual display mode	 1920x1200p60 2560x1440p60 2560x1600p60 Note: resolution and refresh rate may change in situations where there is a bad link or strict limits on TDP YCbCr and RGB The following color depths are supported 8 bits per color The Output interface (Display Port Multi- Stream Transport, DP MST) has the ability to support dual display mode – splitting the video stream is based on external HW (with monitors that can support it, a daisy chain approach can be used to support dual display mode)
Multiple Display Stream Support (MST)	The following dual display mode via MST is supported • 2 x (1280x720) • 2 x (1920x1080) • 2 x (1920x1200) 1920x1080 plus 1920x1200 Support for all relevant Audio formats in Support for all relevant Audio formats in
Audio Pass-Through Support	Pass-Through mode as defined in the WDE specification. LPCM (uncompressed and uncompounded), 2-8 channels, 32KHz – 192KHz, up to 24 bits per sample (dependent on the number of channels)
Independent Digital Audio Out Interface (Sink)	Support for an independent digital Audio Out sink interface, operational upon insertion of an audio peripheral, and not dependent on monitor state (On/Off/Powered-Off) • 4 x I2S Interfaces • Multiplexed with • S/PDIF Interface
Selection of Independent Audio Out Interface	Selection of output interface (I ² S or SPDIF) and on-board audio device capabilities is configurable on a system basis through module Flash Configuration. AUX (DP) / DDC (HDMI) channel is
AUX/DDC Channel Interface	supported. Note: FAUX – fast AUX (~7000Mb) is not required.



	Chosen resolution, frame rate, color space, audio capabilities	•	me rate, color space es based on ed monitor	
	Hot Plug		gh hot plug detection	
Wireless Serial Extension (WSE) for support of USB data flow over wireless link	WGA WSE support	is not supported USB PAL (WSE) versi	on 1.2 (June 2013)	
	WSE Supported USB Ports	Single USB 2.0/3.0 R	oot Port	
	USB Hub	USB Hub device. Any	e does not support USB device ng. Any Dock device must be self- ed or powered from an external b in the Dock Device. The module ble of managing the powering ments of USB devices connected to ck USB Hub external to the module. vices listed in 'Supported USB erals over USB' below are ted, separately and aneously. It supports control, pt, bulk and isochronous flows on the supported device	
	Port Powering	powering. Any Dock powered or powered USB Hub in the Dock is capable of manag requirements of USE		
	WSE Supported Devices	Peripherals over USI supported, separate simultaneously. It s interrupt, bulk and is		
	Number of USB devices	At least 12 USB devices		
	supported on Dock device			
	Number of USB Hub Tiers supported	to the external Hub	number of Hub Tiers connected rnal Hub in the Dock device is r will only support non Hub	
	Supported USB peripherals over WSE	Device Class	Comment	
		HID	Supported	
		Printer	Supported	
		Communication Device Class (CDC)	Supported	
		Mass Storage Class (MSC)	Supported	



HP Elite x2 1012 G2

Technical Specifications

Hub	Supported
Audio Class	Supported
USB Video Class (UVC)	Supported

* Wireless access point and Internet service required. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

Intel® Dual band wireless-AC 8265 802.11AC 2x2 WiFi + BT 4.2 Combo Adaptor (non-vPro™)

Wireless LAN	IEEE 802.11a		
Standards	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
Interoperability	Wi-Fi certified		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
	Note:		
	The FCC has declared as of January 1,		
	2015 products that utilize passive		
	scanning on channel 12/13 and are		
	capable of transmitting must fully		
	comply with requirements of 15.247 or		
	otherwise disable those channels.		
	802.11a/n		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
	Note: Indonesia no support this band)		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54		
	Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54		
	Mbps		
	 802.11n: MCS 0 ~ MCS 15, (20MHz, 		
	and 40MHz)		
	• 802.11ac : MCS0 ~ MCS9, (1SS, and		
	2SS) (20MHz, 40MHz, and 80MHz)		
Modulation	Direct Sequence Spread Spectrum		
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ¹	IEEE and WiFi compliant 64 / 128 bit WEP		
-	encryption for a/b/g mode only		



	• AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-
	PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	Cisco Certified Extensions, all versions
	through CCX4 and CCX Lite
	WAPI
Network Architecture	• WAPI Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access
	points
Output Power ²	• 802.11b : +16dBm minimum
	• 802.11g : +14dBm minimum
	• 802.11a : +14dBm minimum
	• 802.11n HT20(2.4GHz) : +14dBm
	minimum
	• 802.11n HT40(2.4GHz) : +12dBm
	minimum
	• 802.11n HT20(5GHz) : +14dBm minimum
	 802.11n HT40(5GHz) : +12dBm minimum
Power Consumption	Transmit: 2.0 W (max)
rower consumption	Receive: 1.6 W (max)
	Idle mode (PSP): 180 mW (WLAN Associated)
	Idle mode: 50 mW (WLAN unassociated)
	Connect Standby: 10 mW (WLAN+BT)
	Radio disabled: 5 mW
Power Management	ACPI and PCI Express compliant power
	management
	802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps : -94dBm maximum
	802.11b, 11Mbps : -86dBm maximum
	802.11g, 6Mbps : -88dBm maximum 802.11g, 54Mbps : -74dBm maximum
	802.11a, 6Mbps : -88dBm maximum
	802.11a, 54Mbps : -74dBm maximum
	802.11n, MCS07 : -69dBm maximum
	802.11n, MCS15 : -66dBm maximum
	802.11ac, 1SS, MCS-0 : -86dBm maximum
	802.11ac, 1SS, MCS-9 : -61dBm maximum
	802.11ac, 2SS, MCS-0 : -83dBm maximum
	802.11ac, 2SS, MCS-9 : -58dBm maximum
Antenna type	High efficiency antenna with spatial diversity,
Antenna type	mounted in the display enclosure



Technical Specifications

I WO EMDEdded dual Dand 2.4/5 GHZ antennas are					
	provided to the card to support WLAN MIMO				
Form Factor	communications and Bluetooth communications				
Dimensions	PCI-Express M.2 MiniCard				
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm Or				
		x 16.0 x 30.0 mm			
Weight	Type 2230 : 2.8g				
weight	Or				
	Type 1630 : 2q				
Operating Voltage	3.3v +/- 9%				
Temperature	Operating	14° to 158° F (–10	° to 70° C)		
	Non-operating	-40° to 176° F (-4			
Humidity	Operating	10% to 90% (non-			
-	Non-operating	5% to 95% (non-c	-		
Altitude	Operating	0 to 10,000 ft (3,0	48 m)		
	Non-operating	0 to 50,000 ft (15,	240 m)		
LED Activity	LED Amber – Ra	dio OFF; LED White – R	adio ON		
1. Check latest so security featur		ase for updates on sup	ported		
		by country according	to local		
	tivity is mossured a	it a packet error rate o	f 8% for		
		backet error rate of 10			
	DM modulation).				
, j (
HP Integrated M	odule with Blueto	oth 4.0/4.1/4.2 Wirele	ess Technology		
Bluetooth Speci		4.0/4.1/4.2 Compliar			
Frequency Band		2402 to 2480 MHz	-		
• •	Number of Available Channels Legacy : 0~79 (1 MHz/CH)				
		BLE : 0~39 (2 MHz/CH			
Data Rates and	Throughput	Legacy : 3 Mbps data	rate; throughput u	p to 2.17 Mbps	
		BLE : 1 Mbps data rat	te; throughput up to	o 0.2 Mbps	
		Legacy : Synchronou	s Connection Orien	ted links up to 3, 64 kbps	, voice
		channels			
				links 2178.1 kbps/177.1	kbps
		asymmetric (3-DH5)	or 864 kbps symm	etric (3-EV5)	
Transmit Power		The Bluetooth comp	onent shall operate	as a Class II Bluetooth d	evice
		with a maximum tran	nsmit power of + 4	dBm for BR and EDR.	
		·			
Receiver Sensiti	vity	Modulation	0.01% BER	0.001% BER	
Legacy		GFSK	-80 dBm	-70 dBm	
		π/4-DQPSK	-80 dBm	-70 dBm	
		8DPSK	-80 dBm	-70 dBm	
Power Consump	tion	Peak (Tx) 330 mW			
		Peak (Rx) 230 mW			
		Selective Suspend 17	7 mW		

Two embedded dual band 2.4/5 GHz antennas are



Technical Specifications

Legacy Up to 33 ft (10 m)
BLE Up to 99 ft (30 m)
USB 2.0 compliant
Microsoft Windows Bluetooth Software
Point to Point, Multipoint Pico Nets up to 7 slaves
Full support of Bluetooth Security Provisions
Microsoft Windows ACPI, and USB Bus Support
Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff
All necessary regulatory approvals for supported countries, including:
FCC (47 CFR) Part 15C, Section 15.247 & 15.249
ETS 300 328, ETS 300 826
Low Voltage Directive IEC950
UL, CSA, and CE Mark
Serial Port Profile (SPP) ¹
Service Discovery Application Profile (SDAP)
Dial-Up Networking (DUN) ^{1,2}
Generic Object Exchange Profile (GOEP) ^{1,2}
Object Push Profile (OPP) ^{1,2}
Hard Copy Cable Replacement (HCRP) ^{1,2}
Personal Area Networking Profile (PAN) ^{1,2}
Human Interface Device Profile (HID) ^{1,2}
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)
Audio Video Remote Control Profile (AVRCP)
V4.1: ESR5/6/7 compliant

V4.2: ESR8 compliant, LE Secure Connection – Basic.

* Wireless access point and Internet service required. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

Intel® Dual band wireless-AC 8265 802.11AC 2x2 WiFi + BT 4.2 Combo Adaptor (VPro)

Wireless LAN	IEEE 802.11a
Standards	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
Interoperability	Wi-Fi certified



Technical Specifications	
Frequency Band	 802.11b/g/n 2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels. 802.11a/n 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.825 - 5.850 GHz Note: Indonesia no support this band)
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹ Network Architecture	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2- PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI Ad-hoc (Peer to Peer)
Models Roaming	Infrastructure (Access Point Required)
Conting	IEEE 802.11 compliant roaming between access points • 802.11b : +16dBm minimum • 802.11g : +14dBm minimum

Power Consumption	 802.11n minimum 802.11n minimum 802.11n 802.11n 	HT40(2.4GHz) : +12dBm
Power consumption	Receive: 1.6 W	(max)
		180 mW (WLAN Associated) nW (WLAN unassociated)
		10 mW (WLAN UNASSOCIATED)
	Radio disabled: 5	
Power Management	-	ess compliant power
	management 802 11 compliant	power saving mode
Receiver Sensitivity ³		-94dBm maximum
	-	: -86dBm maximum
	J. 1	-88dBm maximum
	•	: -74dBm maximum -88dBm maximum
	· •	: -74dBm maximum
		-69dBm maximum
		-66dBm maximum
	802.11ac, 1SS, MC	S-0 : -86dBm maximum
		S-9:-61dBm maximum
		S-0:-83dBm maximum
Antenna type		S-9 : -58dBm maximum tenna with spatial diversity,
Antenna type	mounted in the di	
		al band 2.4/5 GHz antennas are
	•	rd to support WLAN MIMO
		and Bluetooth communications
Form Factor Dimensions	PCI-Express M.2 M Type 2230 : 2.3 x 2	
Dimensions	Or	22.0 X 50.0 mm
	Type 1630 : 2.3 x	16.0 x 30.0 mm
Weight	Type 2230 : 2.8g	
	Or	
On eventing Voltage	Type 1630 : 2g 3.3v +/- 9%	
Operating Voltage Temperature	Operating	14° to 158° F (–10° to 70° C)
i chiper atare	Non-operating	-40° to 176° F (-40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)



Technical Specifications

LED Activity

LED Amber – Radio OFF; LED White – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluete	ooth 4.0/4.1/4.2 Wireless Technology
Bluetooth Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH)
	BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.

Receiver Sensitivity	Modulation	0.01% BER	0.001% BER
Legacy	GFSK	-80 dBm	-70 dBm
	π/4-DQPSK	-80 dBm	-70 dBm
	8DPSK	-80 dBm	-70 dBm
Power Consumption	Peak (Tx) 330 mW		
	Peak (Rx) 230 mW		
	Selective Suspend 1	7 mW	
Range	Legacy Up to 33 ft (10 m)		
	BLE Up to 99 ft (30 r	n)	
Electrical Interface	USB 2.0 compliant		
Bluetooth Software Supported	Microsoft Windows I	Bluetooth Software	<u>!</u>
Link Topology			
Electrical Interface	Point to Point, Multi	point Pico Nets up t	o 7 slaves
Bluetooth Software Supported	,		
Security			
	Full support of Blue	tooth Security Prov	isions
Power Management	Microsoft Windows	-	
Certifications			
	Self-configurable to	optimize power co	nservation in all oper
	modes, including Sta	• •	•
Security		•	supported countries,
Certifications	FCC (47 CFR) Part 15		
Bluetooth Profiles Supported		, section 15.247 c	~

Technical Specifications

Power Management	ETS 300 328, ETS 300 826	
Certifications	Low Voltage Directive IEC950	
	UL, CSA, and CE Mark	
	Serial Port Profile (SPP) ¹	
	Service Discovery Application Profile (SDAP)	
	Dial-Up Networking (DUN) ^{1,2}	
Certifications	Generic Object Exchange Profile (GOEP) ^{1,2}	
Bluetooth Profiles Supported	Object Push Profile (OPP) ^{1,2}	
Bluetooth Fromes Supported	Hard Copy Cable Replacement (HCRP) ^{1,2}	
	Personal Area Networking Profile (PAN) ^{1,2}	
	Human Interface Device Profile (HID) ^{1,2}	
	Hands Free Profile (HFP)	
	Advanced Audio Distribution Profile (A2DP)	
	Audio Video Remote Control Profile (AVRCP)	
Bluetooth V4.1/V4.2 support	V4.1: ESR5/6/7 compliant	
feature	V4.2: ESR8 compliant, LE Secure Connection – Basic	

* Wireless access point and Internet service required. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

POWER

HP 45 W USB Type-C™ AC	Dimensions	62.0x62.0x28.5mm
adapter	Weight	unit: 220g +/- 10g
	Input	
		Input Efficiency
		Average Efficiency of 25%, 50%, 75%,
		100% load
		condition with 115Vac/230Vac Spec:
		5V : 81.5%
		9V : 86.7%
		10V : 87.5%
		12V : 87.8%
		15V : 87.8%
		20V : 87.8%
		Input frequency range
		47 ~ 63 Hz
		Input AC current
		Max. 1.4 A at 90 Vac
	Output	Output power
		5V/15W
		9V/27W
		10V/37.5W
		12V/45W



Technical Specifications

		15V/45W
		20V/45W
		DC output
		5V/9V/10V/12V/15V/20V
		Hold-up time
		5ms at 115 Vac input
		Output current limit
		<5.0A
	Connector	USB Type-C
	Environmental Design	Operating temperature 32oFto 95oF (Ooto 35oC)
		Non-operating (storage) temperature -4oFto 185oF (-20oto 85oC)
		Altitude
		0 to 16,400 ft (0 to 5000m)
		Humidity
		20% to 95%
		Storage Humidity
	FMI and Cafatu	10% to 95%
	EMI and Safety Certifications	*CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1,
		SELV; Agency
		approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B,
		CISPR22 Class
		B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.
HP 65 W USB Type-C™ AC	Dimensions	74x74x28.5mm
adapter	Weight	unit: 245g +/- 10g
	Input	
		Input Efficiency
		81.5% min at 115 Vac/ 230Vac @ 5V/3A
		86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A
		88% min at 115 Vac/ 230Vac @ 12V/5A
		89% min at 115 Vac/ 230Vac @
		15V/4.33A
		89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range 47 ~ 63 Hz
		Input AC current
		1.7 A at 90 VAC and maximum load
	Output	Output power



	C E M				
	65W				
	=	DC output 5V/9V/10V/12V/15V/20V			
	Hold-up time				
	5ms at 115 Vac in	put			
	Output current li	-			
	<8.0A				
Connector	USB Type C				
Environmental Des	ign Operating tempe	Operating temperature			
	32oFto 95oF (Ooto 35oC)				
		Non-operating (storage) temperature -4oFto 185oF (-20oto 85oC)			
	Altitude				
	0 to 16,400 ft (0 to	0 to 16,400 ft (0 to 5000m)			
	Humidity	Humidity			
	5% to 95%	5% to 95%			
		Storage Humidity			
	5% to 95%				
EMI and Safety		*CE Mark - full compliance with LVD and EMC directives			
Certifications		* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC			
		Class B, CCC, NOM-1 NYCE.	LINAN, ENJJUZZ CI355 D, FCC		
		,000 hours at 25°C ambient co	ondition.		
HP 4-cell Polymer Battery (47 WHr)	Dimensions (H x W x L)	4.46 x 265.6 x 81.15 mm			
		0.18 x 10.45 x 3.2 inch			
	Weight Cells/Type	0.195 kg/0.88 lb Li-ion/Polymer cell			
		-			
	Energy	Voltage : 7.7V Amp-hour capacity: 6.11Ah			
		Watt-hour capacity: 47 WHr			
	Watt-hour capacity				
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)		
		Operating (Discharging)	14° to 140° F (-10° to 60° C		
		Non-operating	-4° to 140° F (-20° to 60° C)		
	Battery recharge time	System in OFF or Standby Mode <3 hours			
	Fuel Gauge LED	No			
	Optional travel battery available	No			



Technical Specifications

COUNTRY OF ORGIN

China

CLEANING

The following cleaning solutions, if used as instructed in the user guide, will not harm the surface of the HP Elite x2 1012 G2 Collaboration Keyboard:

- Dimethyl benzyl ammonium chloride 0.3 percent maximum concentration (for example, disposable wipes, which come in a variety of brands)
- Alcohol-free glass-cleaning fluid
- Solution of mild soap and water
- Dry microfiber cleaning cloth or a chamois (static-free cloth without oil)
- Static-free cloth wipes

Please refer to the user guide that came with your product for detailed instructions about how to clean your HP Elite x2 1012 G2 using these solutions.

The following cleaning solutions, if used as instructed in the user guide, will not harm the surface of HP Elite x2 1012 Travel Keyboard and the HP Elite x2 1012 Advanced Keyboard:

Surface side of the keyboards:

- Dimethyl benzyl ammonium chloride 0.3 percent maximum concentration (for example, disposable wipes, which come in a variety of brands)
- Alcohol-free glass-cleaning fluid
- Solution of mild soap and water
- Dry microfiber cleaning cloth or a chamois (static-free cloth without oil)
- Static-free cloth wipes



Options and Accessories (sold separately and availability may vary by country)

Category	Description	Part number	
Cases	HP Elite Top Load Colombian Leather Case	Т9Н72АА	
	HP Elite Top Load Herringbone Nylon Case	Т9Н7ЗАА	
	HP Elite x2 1012 G2 Protective Case	1HM07AA	
Docking	HP Advanced Wireless Docking Station (requires WiGig)	F7M97AA	
	HP Elite 90W Thunderbolt 3 Dock	1DT93AA	
	HP Elite USB-C Desk Dock G2	Z9R42AA	
	HP Elite USB-C Docking Station	X7W54AA	
	HP USB-C Travel HUB	Z9G82AA	
Input Devices	HP Elite x2 1012 G2 Collaboration Keyboard	1FV39A	
	HP Active Pen with Bluetooth App Launch Button	T4Z24AA	
	HP USB Type-C to VGA Adapter	N9К76АА	
	HP USB Type-C to HDMI Adapter	N9K77AA	
	HP USB Type-C to DisplayPort Adapter	N9K78AA	
	HP USB Type-C to Gigabit Ethernet Adapter	V8Y76AA	
Power	HP 45W USB-C Auto Adapter	Z3Q87AA	
Security	HP Nano Keyed Cable Lock	1AJ39AA	
	HP Nano Master Keyed Cable Lock	1AJ40AA	
	HP Nano Dual Head Keyed Cable Lock	1AJ41AA	

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Summary of Changes

Date of change:	Version History:	Description of change:	

